3D Semiconductor Packaging Market (By Technology Type: 3D Package-On-Package, 3D Wire-Bonded, 3D Fan-Out Based, 3D Through-Silicon-Via; By Materials Type: Bonding Wire, Organic Substrate, Encapsulation Resin, Leadframe, Ceramic Package, Die Attach Material; By Industry Vertical: Industrial, Electronics, Healthcare, IT & Telecommunication, Automotive & Transport, Aerospace & Defense; By Geography) Global Scenario, Market Size, Outlook, Trend and Forecast, 2015-2024

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Abstracts

Global 3D Semiconductor Packaging Market is estimated to reach $12 Billion by 2024; growing at a CAGR of 15.2% from 2016 to 2024. 3D semiconductor packaging is an innovative packaging technology of semiconductor chips that are manufactured by stacking and interconnecting of silicon wafers, to perform as a single device. Various features such as reduced space consumption, better overall performance, and enhanced efficiency have increased its penetration across various applications areas such as electronics, healthcare, industrial, and IT & Telecommunication, among others. Heavy spending on research & development by numerous companies and growing adoption of 3D semiconductor packaging across various industries pose an increased demand for 3D semiconductor packaging in the coming years.

Increase in number of portable electronic devices, short replacement period of electronics products, and technological superiorities over 2D packaging technology are the major factors driving the global 3D semiconductor packaging market. However, high

initial capital investment may hamper the market growth. Growing trend of internet of things would provide several growth opportunities for the market in the coming years.

The global 3D semiconductor packaging market is bifurcated by technology, material type and industry vertical. By technology, the market is further segmented into 3D package-on-package, 3D wire-bonded, 3D fan-out based, 3D through-silicon-via, and others. By material type, the market is categorized into bonding wire, organic substrate, encapsulation resin, leadframe, ceramic package, die attach material, and others. By industry vertical, the market is segregated into industrial, electronics, healthcare, IT & telecommunication, automotive & transport, aerospace & defense, and others.

Based on geography, the global 3D semiconductor packaging market is segmented into North America, Europe, Asia-Pacific and (RoW). The U.S., Mexico and Canada are covered under North America wherein Europe covers UK, France, Germany, Italy, and others. Asia-Pacific covers China, India, Japan, South Korea, and others. Rest of the World (RoW) covers South America, Middle East and Africa.

Major companies operating in the 3D semiconductor packaging market are Siliconware Precision Industries Co., Amkor Technology, ASE group, Ltd., SÜSS MicroTec AG., International Business Machines Corporation (IBM), Jiangsu Changjiang Electronics Technology Co. Ltd., Qualcomm Technologies, Inc., Intel Corporation, STMicroelectronics, and Taiwan Semiconductor Manufacturing Company, among others.

THE KEY TAKEAWAYS FROM THE REPORT

The report will provide detailed analysis of 3D Semiconductor Packaging Market with respect to major segments such as technology type, materials type, and industry vertical type

The report will include the qualitative and quantitative analysis with market estimation over 2015-2024 and compound annual growth rate (CAGR) between 2016 and 2024

Comprehensive analysis of market dynamics including factors and opportunities of the global 3D Semiconductor Packaging Market

An exhaustive regional analysis of 3D Semiconductor Packaging

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Market from 2015 to 2024 will be included in the report

Profile of the key players in the 3D Semiconductor Packaging Market, will be provided, which include key financials, product & services, new developments and business strategies

Scope of 3D Semiconductor Packaging Market

Technology Type Segments

3D package-on-package

3D wire-bonded

3D fan-out based

3D through-silicon-via

Others

Materials Type Segments

Bonding wire

Organic substrate

Encapsulation resin

Leadframe

Ceramic package

Die attach material

Others

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Industry Vertical Type Segments

- Industrial
- Electronics
- Healthcare
- IT & telecommunication
- Automotive & transport
- Aerospace & defense
- Others

Geographical Segments

- North America
  - US
  - Canada
  - Mexico
- Europe
  - UK
  - Germany
  - France
  - Italy
  - Others

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Asia-Pacific

- India
- China
- Japan
- South Korea
- Others

RoW

- South America
- Middle East
- Africa

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